

Topic 3

Memory Management and Access



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Academic Year 14/15

(ver 25-10-2014)

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- 3.6. Cortex-M3 Memory Map
- 3.7. The External Memory Controller (EMC)
- 3.8. The Memory Protection Unit (MPU)

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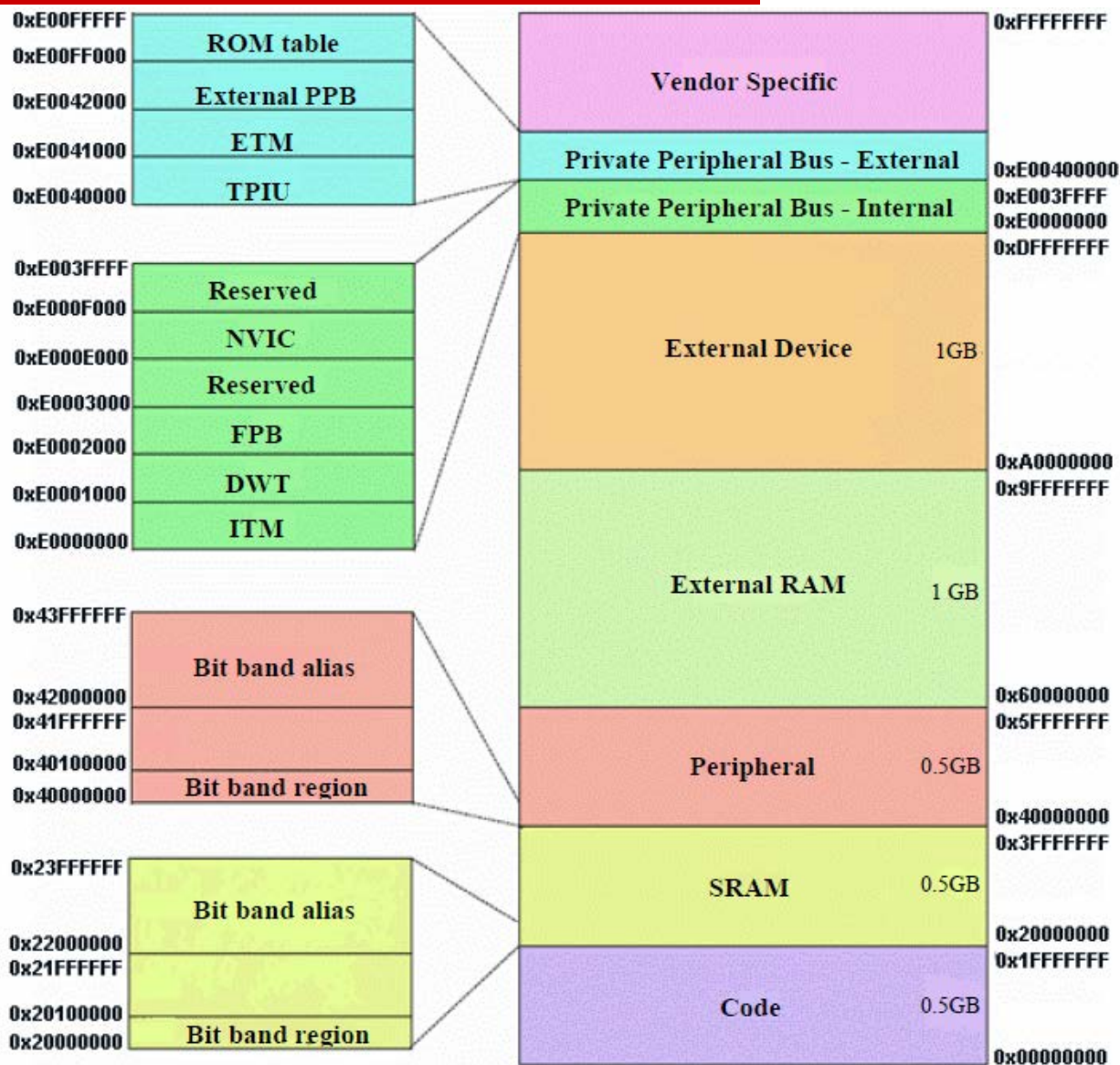
3.8. The Memory Protection Unit (MPU)

3.8.1. Registers

3.6.1. Cortex-M3 Memory Map: The Map

- ❑ The Cortex-M3 has a 4Gbyte predefined memory map
 - Built-in peripherals, NVIC, debugging units, ... can be accessed by simple memory access instructions
- ❑ Memory space is divided
 - C-M3 design has an internal bus infrastructure optimized for this memory usage
- ❑ **Portability is ensured** also among different manufacturers
 - Though different unused parts in the memory maps change among the different devices:
for example, LPC1850 has more external memory map than LPC1788

3.6.1. Cortex-M3 Memory Map: LPC17xx Map



3.6.1. Cortex-M3 Memory Map: LPC17xx Map



Table 3. LPC17xx memory usage and details

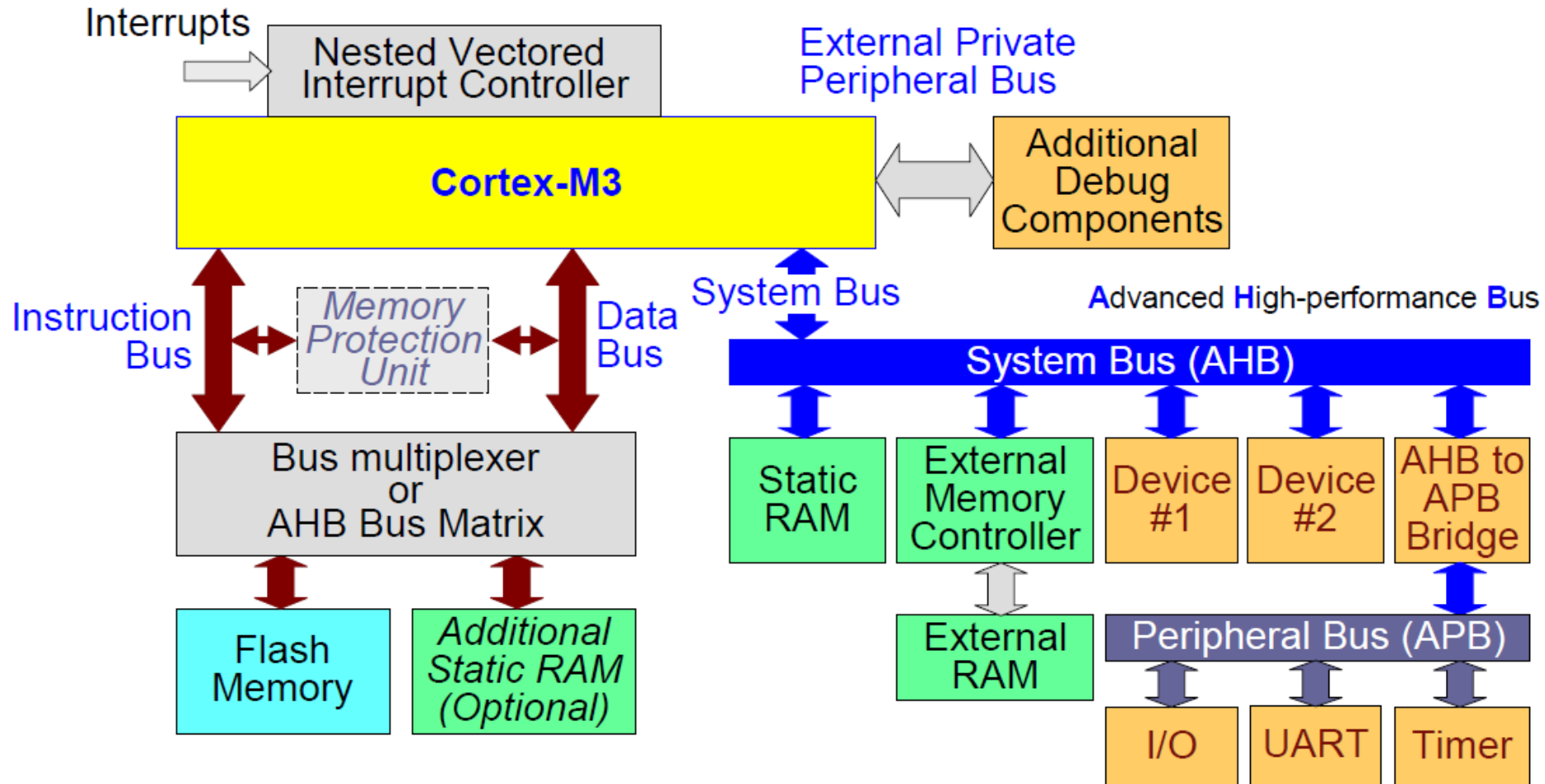
Address range	General Use	Address range details and description	
0x0000 0000 to 0x1FFF FFFF	On-chip non-volatile memory	0x0000 0000 - 0x0007 FFFF	For devices with 512 kB of flash memory.
		0x0000 0000 - 0x0003 FFFF	For devices with 256 kB of flash memory.
		0x0000 0000 - 0x0001 FFFF	For devices with 128 kB of flash memory.
		0x0000 0000 - 0x0000 FFFF	For devices with 64 kB of flash memory.
		0x0000 0000 - 0x0000 7FFF	For devices with 32 kB of flash memory.
	On-chip SRAM	0x1000 0000 - 0x1000 7FFF	For devices with 32 kB of local SRAM.
		0x1000 0000 - 0x1000 3FFF	For devices with 16 kB of local SRAM.
		0x1000 0000 - 0x1000 1FFF	For devices with 8 kB of local SRAM.
	Boot ROM	0x1FFF 0000 - 0x1FFF 1FFF	8 kB Boot ROM with flash services.
	0x2000 0000 to 0x3FFF FFFF	On-chip SRAM (typically used for peripheral data)	0x2007 C000 - 0x2007 FFFF
0x2008 0000 - 0x2008 3FFF			AHB SRAM - bank 1 (16 kB), present on devices with 64 kB of total SRAM.
GPIO		0x2009 C000 - 0x2009 FFFF	GPIO.
0x4000 0000 to 0x5FFF FFFF	APB Peripherals	0x4000 0000 - 0x4007 FFFF	APB0 Peripherals, up to 32 peripheral blocks, 16 kB each.
		0x4008 0000 - 0x400F FFFF	APB1 Peripherals, up to 32 peripheral blocks, 16 kB each.
	AHB peripherals	0x5000 0000 - 0x501F FFFF	DMA Controller, Ethernet interface, and USB interface.
0xE000 0000 to 0xE00F FFFF	Cortex-M3 Private Peripheral Bus	0xE000 0000 - 0xE00F FFFF	Cortex-M3 related functions, includes the NVIC and System Tick Timer.

3.6.2. Cortex-M3 Memory Map: Bus Interfaces



- Cortex M3 has a Harvard architecture, and thus, different bus interfaces
 - Code Memory Buses, I-Code y D-Code: 32 bit buses used to access code memory region, optimized for the fetch operation
 - System Bus (AHB): 32 bit bus used to access data memory region, where RAM, peripherals and some external devices are located. The EMC used to access to external devices are connected to this bus
 - Private Peripheral Bus, PPB: 32 bit bus used to access to the part of the System Level region not accessed through the System Bus, such as debugging units. It has two versions, internal and external (APB)
 - DAP Bus: 32-bit bus specifically used to attach debug interface blocks such as JTAG-DP or SW-DP

3.6.2. Cortex-M3 Memory Map: Bus Interfaces



3.6.2. Cortex-M3 Memory Map: Bus Interfaces

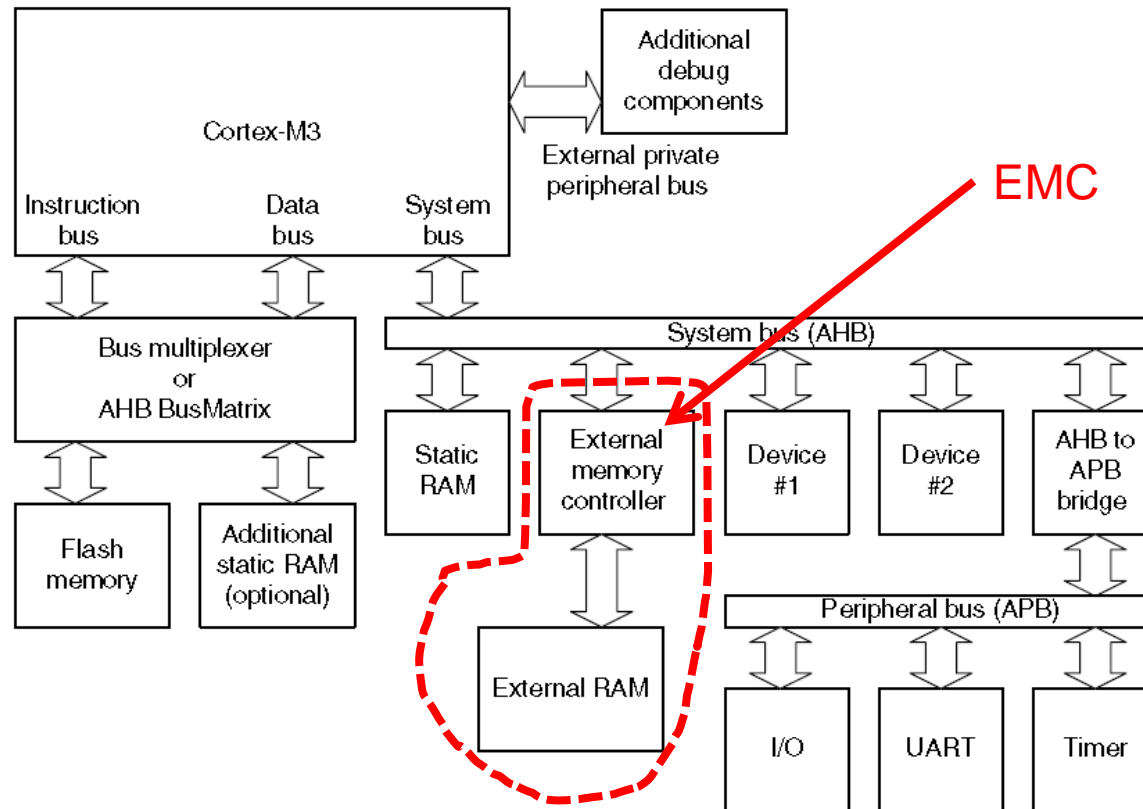


Memory Map	Interface
Code	Instruction fetches are performed over the ICode bus. Data accesses are performed over the DCode bus.
SRAM	Instruction fetches and data accesses are performed over the system bus.
SRAM_bitband	Alias region. Data accesses are aliases. Instruction accesses are not aliases.
Peripheral	Instruction fetches and data accesses are performed over the system bus.
Periph_bitband	Alias region. Data accesses are aliases. Instruction accesses are not aliases.
External RAM	Instruction fetches and data accesses are performed over the system bus.
External Device	Instruction fetches and data accesses are performed over the system bus.
Private Peripheral Bus	<p>Accesses to:</p> <ul style="list-style-type: none"> <i>Instrumentation Trace Macrocell (ITM)</i> <i>Nested Vectored Interrupt Controller (NVIC)</i> <i>Flashpatch and Breakpoint (FPB)</i> <i>Data Watchpoint and Trace (DWT)</i> <i>Memory Protection Unit (MPU)</i> <p>are performed to the processor internal <i>Private Peripheral Bus (PPB)</i>.</p> <p>Accesses to:</p> <ul style="list-style-type: none"> <i>Trace Point Interface Unit (TPIU)</i> <i>Embedded Trace Macrocell (ETM)</i> System areas of the PPB memory map <p>are performed over the external PPB interface.</p> <p>This memory region is <i>Execute Never (XN)</i>, and so instruction fetches are prohibited. An MPU, if present, cannot change this.</p>
System	System segment for vendor system peripherals. This memory region is XN, and so instruction fetches are prohibited. An MPU, if present, cannot change this.

3.7.1. The EMC: General characteristics

◆ What is a External Memory Controller (EMC)?

- EMC is a unit normally included in microcontrollers, designed to manage external implementation and access to the memory map



3.7.1. The EMC: General characteristics

◆ What are the normal tasks of an EMC?

- ◆ Buffering Address, Data and Control busses
- ◆ Implementing Bank enable signals (BLs), ordering data when misalignments or access to different size data
- ◆ Implementing CS signals to enable external sections in the map, allowing software configuration of these sections size and position
- ◆ Dynamic RAM management (refresh and demultiplexing busses)
- ◆ Programming wait cycles and timings, such as setup, strobe, and hold times

◆ Some examples:

- ◆ Cortex M3: LP18xx (NXP), LPC24xx (NXP), MCB2400 (NI), STM32XX (STM)
- ◆ Other devices: μ C MCF52xx ColdFire (Freescale), DSP TMS320C6000 (TI)
- ◆ Stand-alone EMCs: 24815 (Freescale), STM32F10xxx (STM), OPB-EMC (Xilinx)

3.7.2. The EMC: Memory map and connections

◆ In Cortex-M3 processor, included for example in LPC177x/178x

Table 6. LPC178x/177x memory usage and details

Address range	General Use	Address range details and description	
0x0000 0000 to 0x1FFF FFFF	On-chip non-volatile memory	0x0000 0000 - 0x0007 FFFF	For devices with 512 kB of flash memory.
		0x0000 0000 - 0x0003 FFFF	For devices with 256 kB of flash memory.
		0x0000 0000 - 0x0001 FFFF	For devices with 128 kB of flash memory.
		0x0000 0000 - 0x0000 FFFF	For devices with 64 kB of flash memory.
	On-chip SRAM	0x1000 0000 - 0x1000 FFFF	For devices with 64 kB of local SRAM.
		0x1000 0000 - 0x1000 7FFF	For devices with 32 kB of local SRAM.
		0x1000 0000 - 0x1000 3FFF	For devices with 16 kB of local SRAM.
	Boot ROM	0x1FFF 0000 - 0x1FFF 1FFF	8 kB Boot ROM with flash services.
	On-chip SRAM (typically used for peripheral data)	0x2000 0000 - 0x2000 1FFF	Peripheral RAM - bank 0 (first 8 kB)
		0x2002 0000 - 0x2000 3FFF	Peripheral RAM - bank 0 (second 8 kB)
		0x2000 4000 - 0x2000 7FFF	Peripheral RAM - bank 1 (16 kB)
0x2000 0000 to 0x3FFF FFFF	AHB peripherals	0x2008 0000 - 0x200B FFFF	See Figure 6 for details
0x4000 0000 to 0x7FFF FFFF	APB Peripherals	0x4000 0000 - 0x4007 FFFF	APB0 Peripherals, up to 32 peripheral blocks of 16 kB each.
		0x4008 0000 - 0x400F FFFF	APB1 Peripherals, up to 32 peripheral blocks of 16 kB each.
0x8000 0000 to 0xDFFF FFFF	Off-chip Memory via the External Memory Controller	Four static memory chip selects:	
		0x8000 0000 - 0x83FF FFFF	Static memory chip select 0 (up to 64 MB)
		0x9000 0000 - 0x93FF FFFF	Static memory chip select 1 (up to 64 MB)
		0x9800 0000 - 0x9BFF FFFF	Static memory chip select 2 (up to 64 MB)
		0x9C00 0000 - 0x9FFF FFFF	Static memory chip select 3 (up to 64 MB)
		Four dynamic memory chip selects:	
		0xA000 0000 - 0xAFFF FFFF	Dynamic memory chip select 0 (up to 256MB)
		0xB000 0000 - 0xBFFF FFFF	Dynamic memory chip select 1 (up to 256MB)
		0xC000 0000 - 0xCFFF FFFF	Dynamic memory chip select 2 (up to 256MB)
		0xD000 0000 - 0xDFFF FFFF	Dynamic memory chip select 3 (up to 256MB)
0xE000 0000 to 0xE00F FFFF	Cortex-M3 Private Peripheral Bus	0xE000 0000 - 0xE00F FFFF	Cortex-M3 related functions, includes the NVIC and System Tick Timer

3.7.2. The EMC: Memory map and connections

◆ LPC178x:

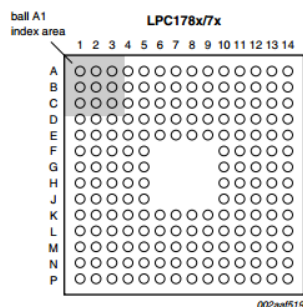
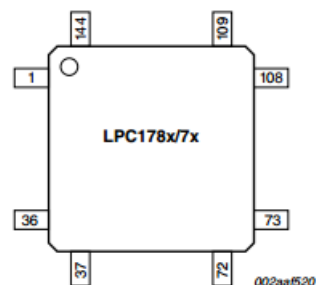
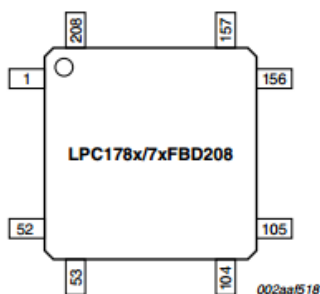


Table 109. EMC configuration

Device package	Data bus widths supported	Pins available	Dynamic memory configuration registers U[2]	Static memory configuration registers U[3]	External memory connections
144-pin	8-bit	EMC_A[15:0] EMC_D[7:0] EMC_OE EMC_WE EMC_CS1:0		EMCStaticConfig1/0 EMCStaticWaitWen1/0 EMCStaticWaitOen1/0 EMCStaticWaitRd1/0 EMCStaticWaitPage1/0 EMCStaticWaitWr1/0 EMCStaticWaitTurn1/0	Section 9.14.3
180-pin	16-bit, 8-bit	EMC_A[19:0] EMC_D[15:0] EMC_OE EMC_WE EMC_BLS1:0 EMC_CS1:0 EMC_DYCS1:0 EMC_CAS EMC_RAS EMC_CLK1:0 EMC_CKE1:0 EMC_DQM1:0	EMCDynamicConfig1/0 EMCDynamicRasCas1/0	EMCStaticConfig1/0 EMCStaticWaitWen1/0 EMCStaticWaitOen1/0 EMCStaticWaitRd1/0 EMCStaticWaitPage1/0 EMCStaticWaitWr1/0 EMCStaticWaitTurn1/0	Section 9.14.2 Section 9.14.3
208-pin	32-bit, 16-bit, 8-bit	EMC_A[25:0] EMC_D[31:0] EMC_OE EMC_WE EMC_BLS3:0 EMC_CS3:0 EMC_DYCS3:0 EMC_CAS EMC_RAS EMC_CLK1:0 EMC_CKE3:0 EMC_DQM3:0	EMCDynamicConfig3/2/1/0 EMCDynamicRasCas3/2/1/0	EMCStaticConfig3/2/1/0 EMCStaticWaitWen3/2/1/0 EMCStaticWaitOen3/2/1/0 EMCStaticWaitRd3/2/1/0 EMCStaticWaitPage3/2/1/0 EMCStaticWaitWr3/2/1/0 EMCStaticWaitTurn3/2/1/0	Section 9.14.1 Section 9.14.2 Section 9.14.3

3.7.2. The EMC: Memory map and connections

◆ LPC177x/178x: External memory map + Pin Signals

0x8000 0000 to 0xDFFF FFFF	Off-chip Memory via the External Memory Controller	Four static memory chip selects:	
		0x8000 0000 - 0x83FF FFFF	Static memory chip select 0 (up to 64 MB)
		0x9000 0000 - 0x93FF FFFF	Static memory chip select 1 (up to 64 MB)
		0x9800 0000 - 0x9BFF FFFF	Static memory chip select 2 (up to 64 MB)
		0x9C00 0000 - 0x9FFF FFFF	Static memory chip select 3 (up to 64 MB)
		Four dynamic memory chip selects:	
		0xA000 0000 - 0xAFFF FFFF	Dynamic memory chip select 0 (up to 256MB)
		0xB000 0000 - 0xBFFF FFFF	Dynamic memory chip select 1 (up to 256MB)
		0xC000 0000 - 0xCFFF FFFF	Dynamic memory chip select 2 (up to 256MB)
		0xD000 0000 - 0xDFFF FFFF	Dynamic memory chip select 3 (up to 256MB)

Table 7. External memory controller pin configuration

Part	Data bus pins	Address bus pins	Control pins	
			SRAM	SDRAM
LPC1788FBD208	EMC_D[31:0]	EMC_A[25:0]	EMC_BLS[3:0], EMC_CS[3:0], EMC_OE, EMC_WE	EMC_RAS, EMC_CAS, EMC_DYCS[3:0], EMC_CLK[1:0], EMC_CKE[3:0], EMC_DQM[3:0]

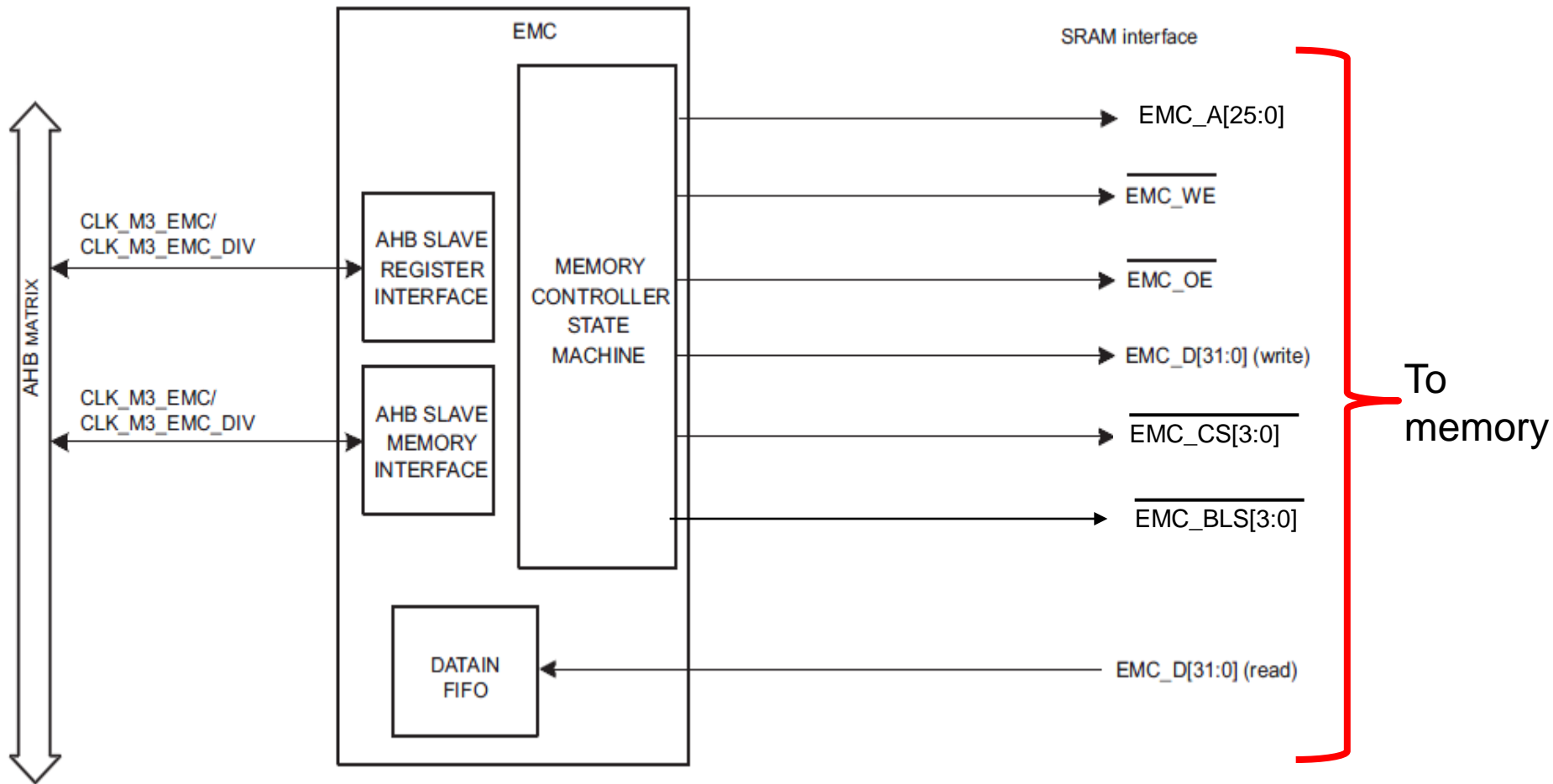
3.7.2. The EMC: Memory map and connections

◆ LPC177x/178x: Pin Signals

Pin function	Direction	Description
EMC_A[25:0]	O	Address bus
EMC_D[31:0]	I/O	Data bus
EMC_BLS[3:0]	O	Byte lane select
EMC_CS[3:0]	O	Static RAM memory bank select
EMC_OE	O	Output enable
EMC_WE	O	Write enable
EMC_CKEOUT[3:0]	O	SDRAM clock enable signals
EMC_CLK[3:0]; EMC_CLK01; EMC_CLK23	O	SDRAM clock signals
EMC_DQMOUT[3:0]	O	Data mask output to SDRAM memory banks
EMC_DYCS[3:0]	O	SDRAM memory bank select
EMC_CAS	O	Column address strobe
EMC_RAS	O	Row address strobe

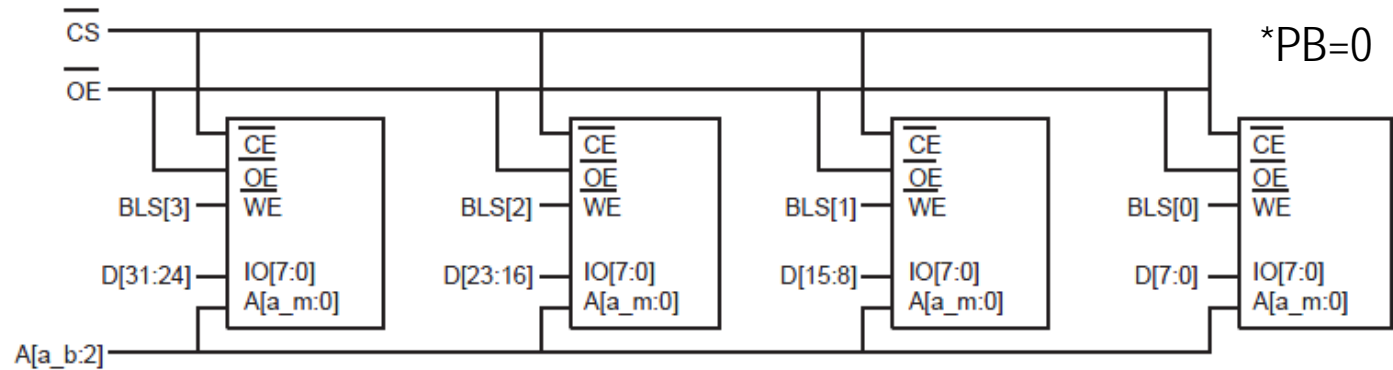
3.7.2. The EMC: Memory map and connections

◆ LPC178x: SRAM interface

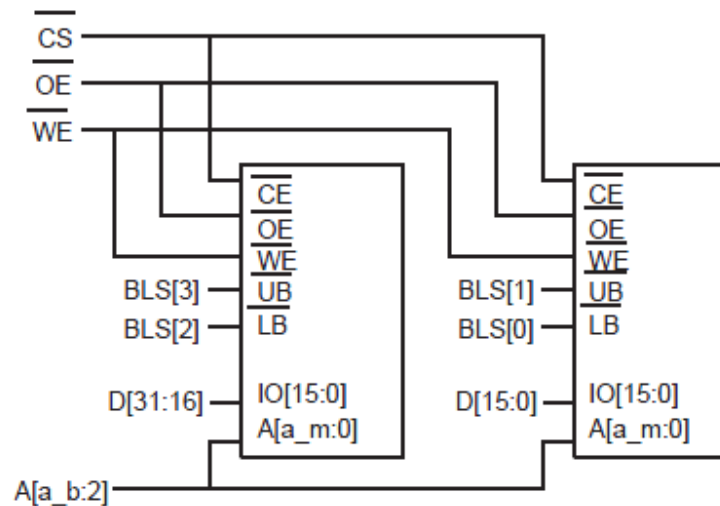


3.7.2. The EMC: Memory map and connections

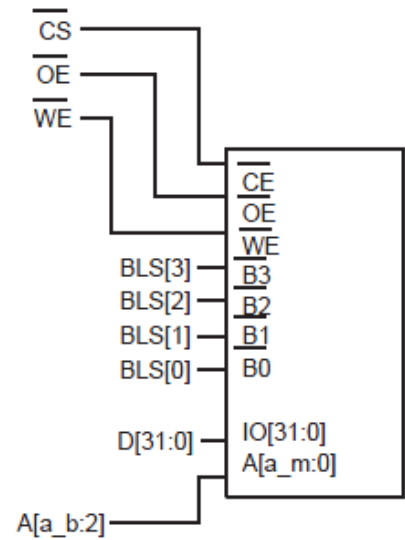
◆ LPC178x: SRAM connection



a. 32 bit wide memory bank interfaced to four 8 bit memory chips



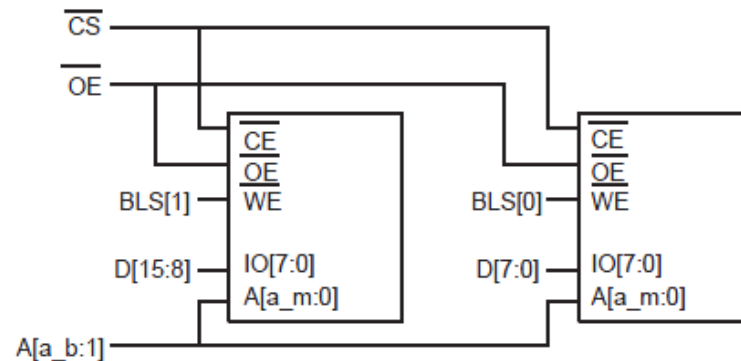
b. 32 bit wide memory bank interfaced to two 16 bit memory chips



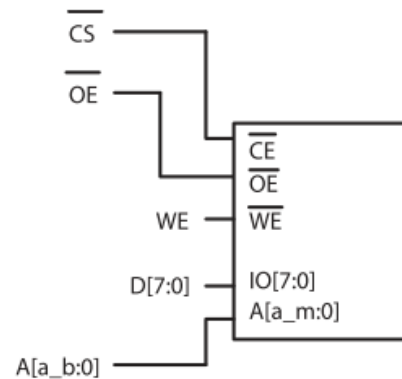
c. 32 bit wide memory bank interfaced to one 8 bit memory chip

3.7.2. The EMC: Memory map and connections

◆ LPC178x: SRAM connection



16 bit wide memory bank interfaced to two 8 bit memory chips

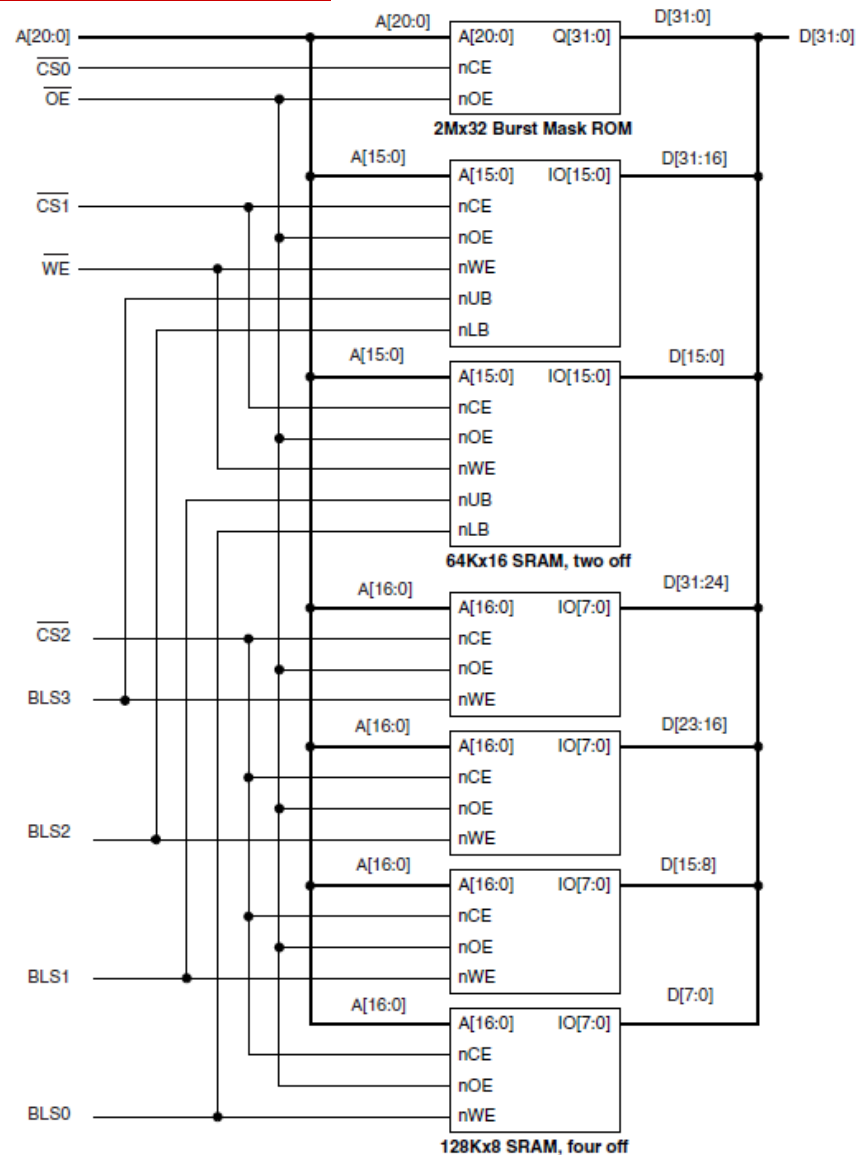


8 bit bank external memory interface (bits MW = 00)

3.7.2. The EMC: Memory map and connections

◆ LPC178x:

Implementation example



3.7.3. The EMC: Registers

- ◆ **EMC configuration** (area enabled, data port width, access delays, ...)
 - ◆ Performed through registers, depending on the external map available, and thus, on the specific device
 - ◆ **In LPC178x:**

Name	Access	Offset	After reset	After boot	Description	
CONTROL	R/W	0x000	0x3	0x1	Controls operation of the memory controller	GENERAL
STATUS	RO	0x004	0x5	0x5	Provides EMC status information	
CNFIG	R/W	0x008	0	0	Configures operation of the memory controller	
STATICEXTENDEDWAIT	R/W	0x80	0	0	Selects time for long static memory read and write transfers	
STATICCONFIG0	R/W	0x200	0	0x81	Selects the memory configuration for chip select 0	For each CS
STATICWAITWEN0	R/W	0x204	0	0	Selects the delay from chip select 0 to a write enable	
STATICWAITOEN0	R/W	0x208	0	0	Selects the delay from chip select 0 or address change, whichever is later, to output enable	
STATICWAITRD0	R/W	0x20C	0x1F	0xE	Selects the delay from chip select 0 to a read access	
STATICWAITPAGE0	R/W	0x210	0x1F	0x1F	Selects the delay for asynchronous page mode sequential accesses for chip select 0	
STATICWAITWR0	R/W	0x214	0x1F	0x1F	Selects the delay from chip select 0 to a write access	
STATICWAITTURN0	R/W	0x218	0xF	0xF	Selects the number of bus turnaround cycles for chip select 0	

3.7.3. The EMC: Registers

◆ EMC configuration in LPC178x: General registers

Name	Description
CONTROL	<ul style="list-style-type: none">• EMC enable• Low-power mode
STATUS	<ul style="list-style-type: none">• Busy. EMC is performing memory transactions, commands, auto-refresh cycles, etc.• Write buffer status. Write buffers contain data• Self-refresh acknowledge. Indicates the operating mode of the EMC, self-refresh or normal
CNFIG	<ul style="list-style-type: none">• Endian mode. Little or big
STATICEXTENDEDWAIT	<ul style="list-style-type: none">• Extended wait time out (10 bits). Reset value: 0x0 = 16 clock cycles Value to be programmed = (memory transfer time x CCLK frequency) / 16 - 1

For example, for a static memory read/write transfer time of 16 μ s, and a CCLK frequency of 50 MHz, the following value must be programmed into this register:
 $(16 \times 10^{-6} \times 50 \times 10^6) / 16 - 1 = 49$.

3.7.3. The EMC: Registers

◆ EMC configuration in LPC178x: For each CS, basic configuration

Name	Description
STATICCONFIG0	<ul style="list-style-type: none">• Memory width (1:0) 0x0: 8 bit (reset) 0x1: 16 bit 0x2: 32 bit• Page mode (3). The EMC can burst up to 4 external accesses 0x0: Async page mode disable (reset) 0x1: Async page mode enabled• Chip select polarity (6) 0x0: Active LOW chip select 0x1: Active HIGH chip select• Byte lane state (7). Enables different types of memory to be connected 0x0: For reads all the bits in BLSn[3:0] are HIGH. For writes all the bits in BLSn[3:0] are LOW 0x1: For reads and writes the respective active bits in BLSn[3:0] are LOW• Extended wait (8). Uses StaticExtendedWait register to time both read and write transfers rather than the StaticWaitRd and StaticWaitWr registers 0x0: Extended wait disabled (reset value) 0x1: Extended wait enabled

3.7.3. The EMC: Registers

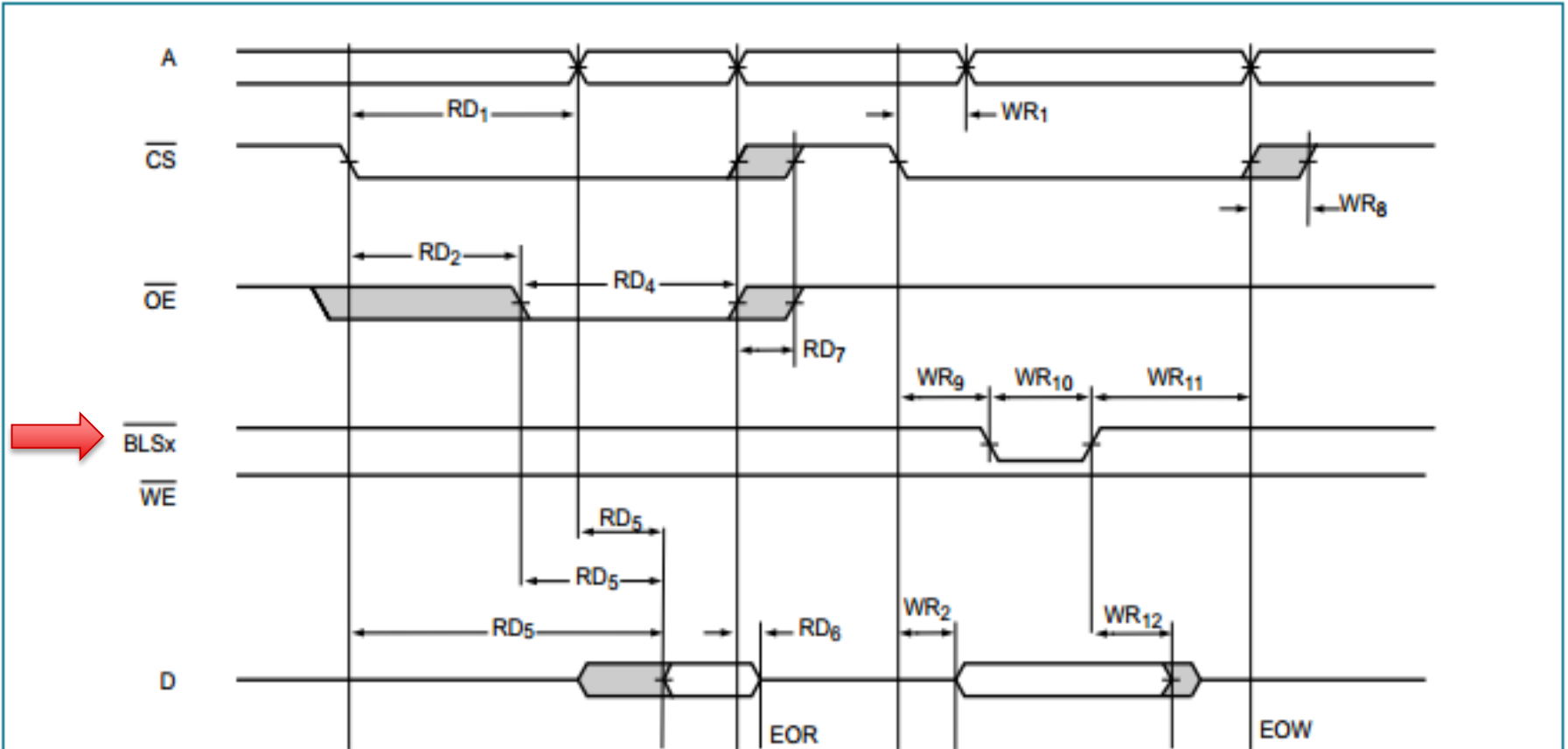
◆ EMC configuration in LPC178x: For each CS, basic configuration

Table 134. Static Memory Configuration registers (STATICCONFIG[0:3], address 0x2009 C200 (STATICCONFIG0), 0x2009 C220 (STATICCONFIG1), 0x2009 C240 (STATICCONFIG2), 0x2009 C260 (STATICCONFIG3)) bit description

Bit	Symbol	Value	Description	Reset Value
1:0	MW		Memory width.	0
		0x0	8 bit (POR reset value).	
		0x1	16 bit.	
		0x2	32 bit.	
		0x3	Reserved.	
2	-		Reserved. Read value is undefined, only zero should be written.	NA
3	PM		Page mode. In page mode the EMC can burst up to four external accesses. Therefore devices with asynchronous page mode burst four or higher devices are supported. Asynchronous page mode burst two devices are not supported and must be accessed normally.	0
		0	Disabled (POR reset value).	
		1	Asynchronous page mode enabled (page length four).	
5:4	-		Reserved. Read value is undefined, only zero should be written.	NA
6	PC		Chip select polarity. The value of the chip select polarity on power-on reset is 0.	0
		0	Active LOW chip select.	
		1	Active HIGH chip select.	
7	PB		Byte lane state. The byte lane state bit, PB, enables different types of memory to be connected. For byte-wide static memories the BLS3:0 signal from the EMC is usually connected to \overline{WE} (write enable). In this case for reads all the BLS3:0 bits must be HIGH. This means that the byte lane state (PB) bit must be LOW. 16 bit wide static memory devices usually have the $\overline{BLS3:0}$ signals connected to the UBn and LBn (upper byte and lower byte) signals in the static memory. In this case a write to a particular byte must assert the appropriate UBn or LBn signal LOW. For reads, all the UB and LB signals must be asserted LOW so that the bus is driven. In this case the byte lane state (PB) bit must be HIGH.	0
		0	For reads all the bits in BLS3:0 are HIGH. For writes the respective active bits in BLS3:0 are LOW (POR reset value).	
		1	For reads the respective active bits in BLS3:0 are LOW. For writes the respective active bits in BLS3:0 are LOW.	

3.7.3. The EMC: Registers

◆ LPC178x: static memory R/W access



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Fig 16. External static memory read/write access (PB = 0)

3.7.3. The EMC: Registers



◆ LPC178x: static memory R/W access

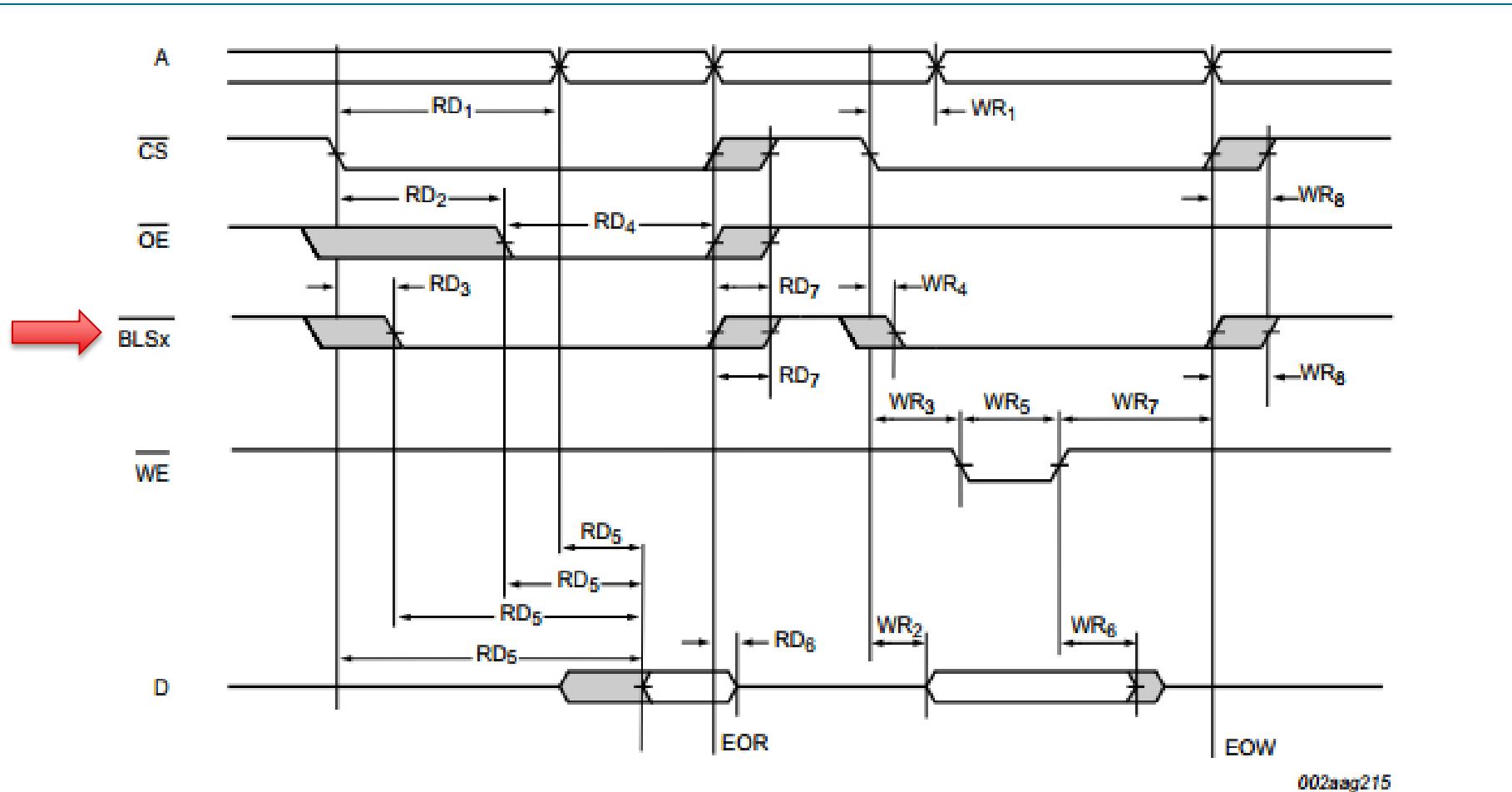


Fig 17. External static memory read/write access (PB = 1)

3.7.3. The EMC: Registers

◆ **EMC configuration in LPC178x:** For each CS, timing configuration

Table 309. Static Memory Write Enable Delay registers (STATICWAITWEN[0:3], address 0x4000 5204 (STATICWAITWEN0), 0x4000 5224 (STATICWAITWEN1), 0x4000 5244 (STATICWAITWEN2), 0x4000 5264 (STATICWAITWEN3)) bit description

Bit	Symbol	Description	Reset value
3:0	WAITWEN	Wait write enable. Delay from chip select assertion to write enable. 0x0 = One CCLK cycle delay between assertion of chip select and write enable (POR reset value). 0x1 - 0xF = (n + 1) CCLK cycle delay. The delay is (WAITWEN + 1) x tCCLK.	0x0
31:4	-	Reserved, user software should not write ones to reserved bits. The value read from a reserved bit is not defined.	-

3.7.3. The EMC: Registers

◆ **EMC configuration in LPC178x:** For each CS, timing configuration

Table 310. Static Memory Output Enable delay registers (STATICWAITOEN[0:3], address 0x4000 5208 (STATICWAITOEN0), 0x4000 5228 (STATICWAITOEN1), 0x4000 5248 (STATICWAITOEN2), 0x4000 5268 (STATICWAITOEN3)) bit description

Bit	Symbol	Description	Reset value
3:0	WAITOEN	Wait output enable. Delay from chip select assertion to output enable. 0x0 = No delay (POR reset value). 0x1 - 0xF = n cycle delay. The delay is WAITOEN x tCCLK.	0x0
31:4	-	Reserved, user software should not write ones to reserved bits. The value read from a reserved bit is not defined.	-

3.7.3. The EMC: Registers

◆ **EMC configuration in LPC178x:** For each CS, timing configuration

Table 311. Static Memory Read Delay registers (STATICWAITRD[0:3], address 0x4000 520C (STATICWAITRD0), 0x4000 522C (STATICWAITRD1), 0x4000 524C (STATICWAITRD2), 0x4000 526C (STATICWAITRD3)) bit description

Bit	Symbol	Description	Reset value
4:0	WAITRD	<p>Non-page mode read wait states or asynchronous page mode read first access wait state.</p> <p>Non-page mode read or asynchronous page mode read, first read only: $0x0 - 0x1E = (n + 1)$ CCLK cycles for read accesses. For non-sequential reads, the wait state time is $(WAITRD + 1) \times t_{CCLK}$. $0x1F = 32$ CCLK cycles for read accesses (POR reset value).</p>	0x1F [1]
31:5	-	Reserved, user software should not write ones to reserved bits. The value read from a reserved bit is not defined.	-

[1] The reset value depends on the boot mode.

3.7.3. The EMC: Registers



◆ EMC configuration in LPC178x: For each CS, timing configuration

Table 312. Static Memory Page Mode Read Delay registers (STATICWAITPAGE[0:3], address 0x4000 5210 (STATICWAITPAGE0), 0x4000 5230 (STATICWAITPAGE1), 0x4000 5250 (STATICWAITPAGE2), 0x4000 5270 (STATICWAITPAGE3)) bit description

Bit	Symbol	Description	Reset value
4:0	WAITPAGE	Asynchronous page mode read after the first read wait states. Number of wait states for asynchronous page mode read accesses after the first read: $0x0 - 0x1E = (n + 1)$ CCLK cycle read access time. For asynchronous page mode read for sequential reads, the wait state time for page mode accesses after the first read is $(WAITPAGE + 1) \times t_{CCLK}$. $0x1F = 32$ CCLK cycle read access time (POR reset value).	0x1F
31:5	-	Reserved, user software should not write ones to reserved bits. The value read from a reserved bit is not defined.	-

3.7.3. The EMC: Registers



◆ EMC configuration in LPC178x: For each CS, timing configuration

Table 313. Static Memory Write Delay registers (STATICWAITWR[0:3], address 0x4000 5214 (STATICWAITWR0), 0x4000 5234 (STATICWAITWR1), 0x4000 5254 (STATICWAITWR2), 0x4000 5274 (STATICWAITWR3)) bit description

Bit	Symbol	Description	Reset value
4:0	WAITWR	Write wait states. SRAM wait state time for write accesses after the first read: 0x0 - 0x1E = (n + 2) CCLK cycle write access time. The wait state time for write accesses after the first read is WAITWR (n + 2) x tCCLK. 0x1F = 33 CCLK cycle write access time (POR reset value).	0x1F
31:5	-	Reserved, user software should not write ones to reserved bits. The value read from a reserved bit is not defined.	-

3.7.3. The EMC: Registers

◆ EMC configuration in LPC178x: For each CS, timing configuration

Table 314. Static Memory Turn-around Delay registers (STATICWAITTURN[0:3], address 0x4000 5218 (STATICWAITTURN0), 0x4000 5238 (STATICWAITTURN1), 0x4000 5258 (STATICWAITTURN2), 0x4000 5278 (STATICWAITTURN3)) bit description

Bit	Symbol	Description	Reset value
3:0	WAITTURN	Bus turn-around cycles. 0x0 - 0xE = (n + 1) CCLK turn-around cycles. Bus turn-around time is (WAITTURN + 1) x tCCLK. 0xF = 16 CCLK turn-around cycles (POR reset value).	0xF
31:4	-	Reserved, user software should not write ones to reserved bits. The value read from a reserved bit is not defined.	-

Bus turn-around cycles are generated between external bus transfers in the following situations when at least one of the memory banks is static memory:

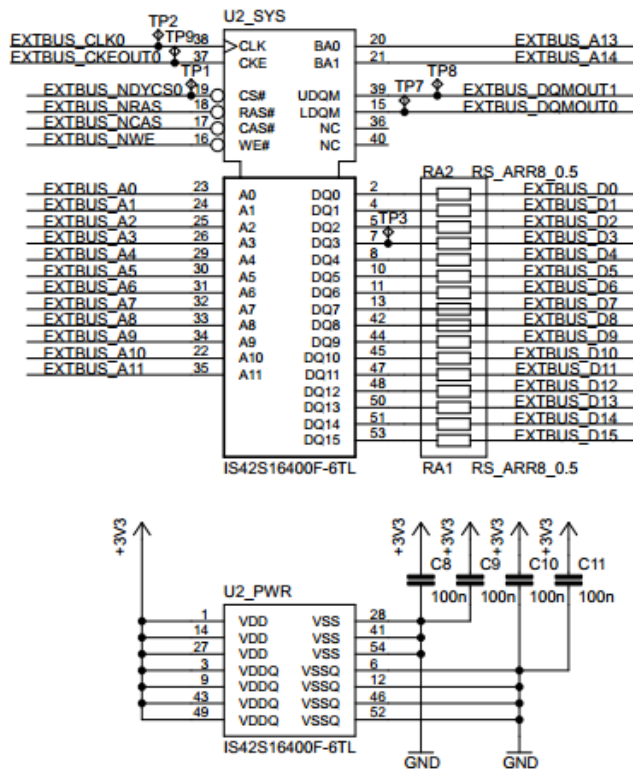
- between read and read to different memory banks
- between read and write to the same memory bank
- between read and write to different memory banks

Bus turn-around cycles prevent bus contention on the external memory data bus.

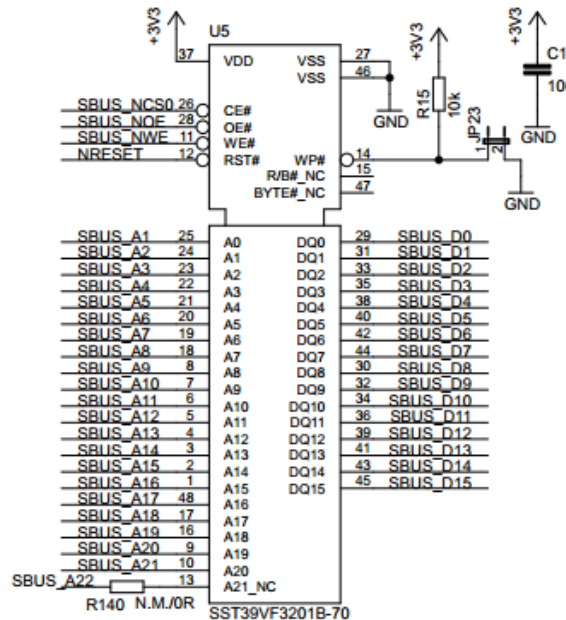
3.7.4. The EMC: Example

◆ Analyze the schematic of external memory in a LPC1850 board:

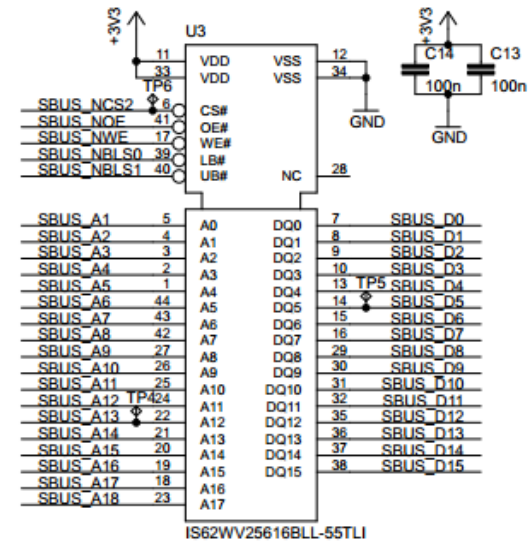
SDRAM



FLASH

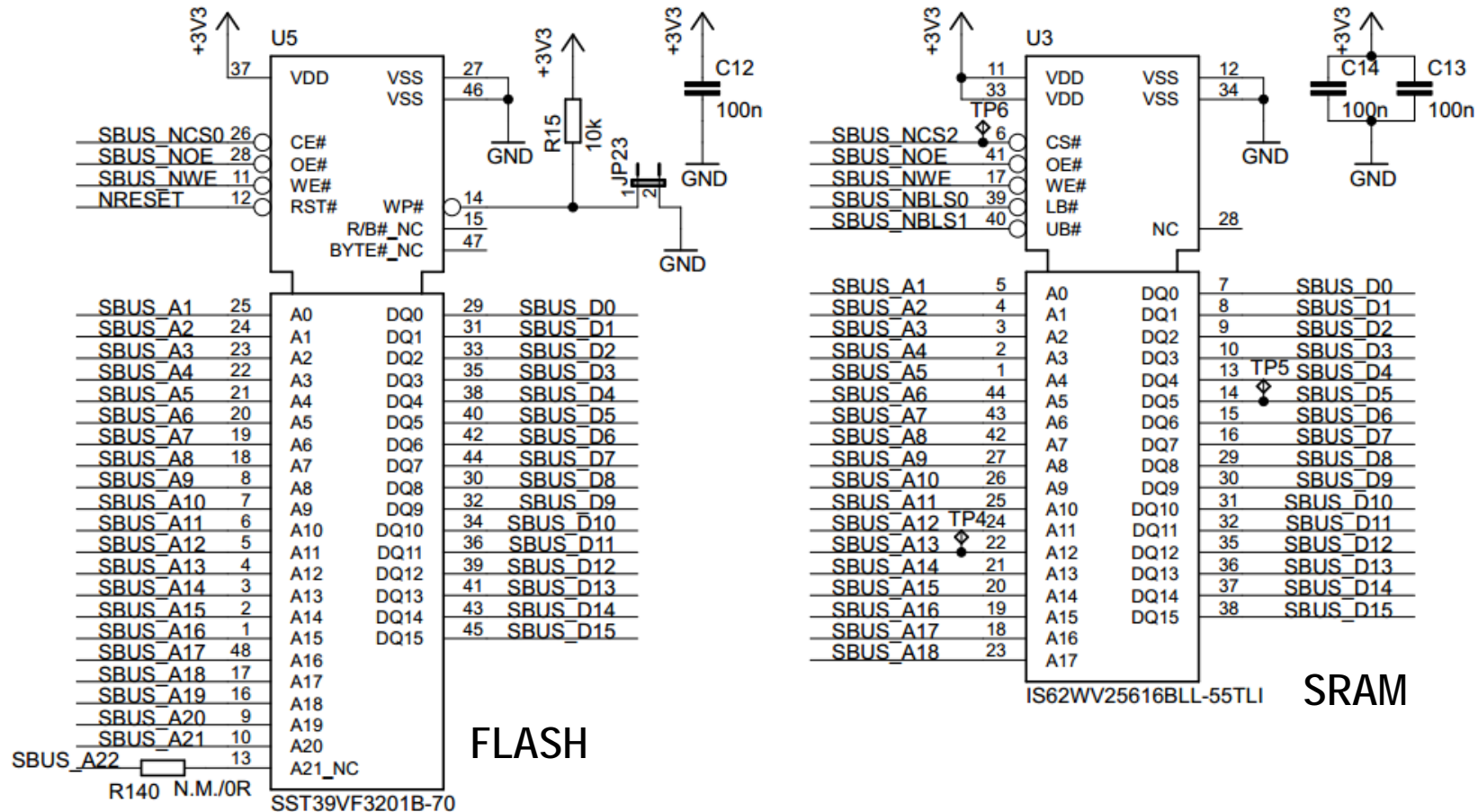


SRAM



3.7.4. The EMC: Example

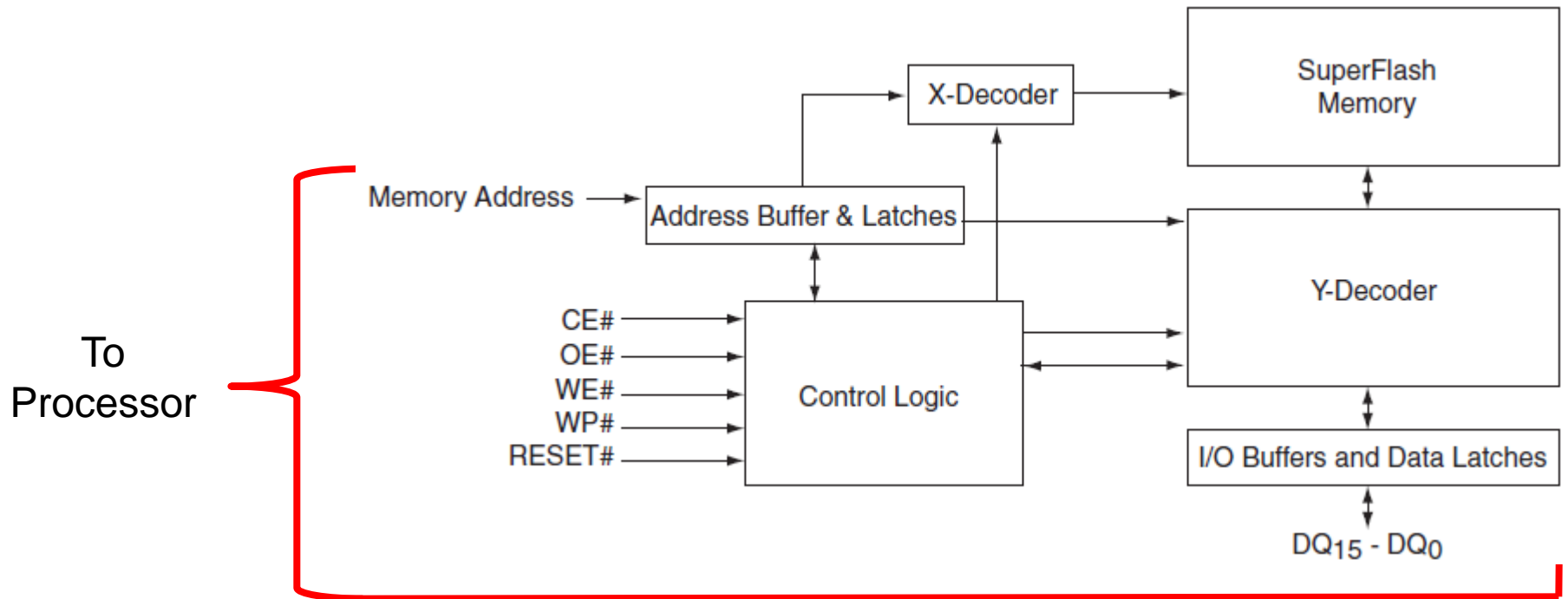
◆ Analyze the schematic of external memory in a LPC1850 board:



3.7.4. The EMC: Example



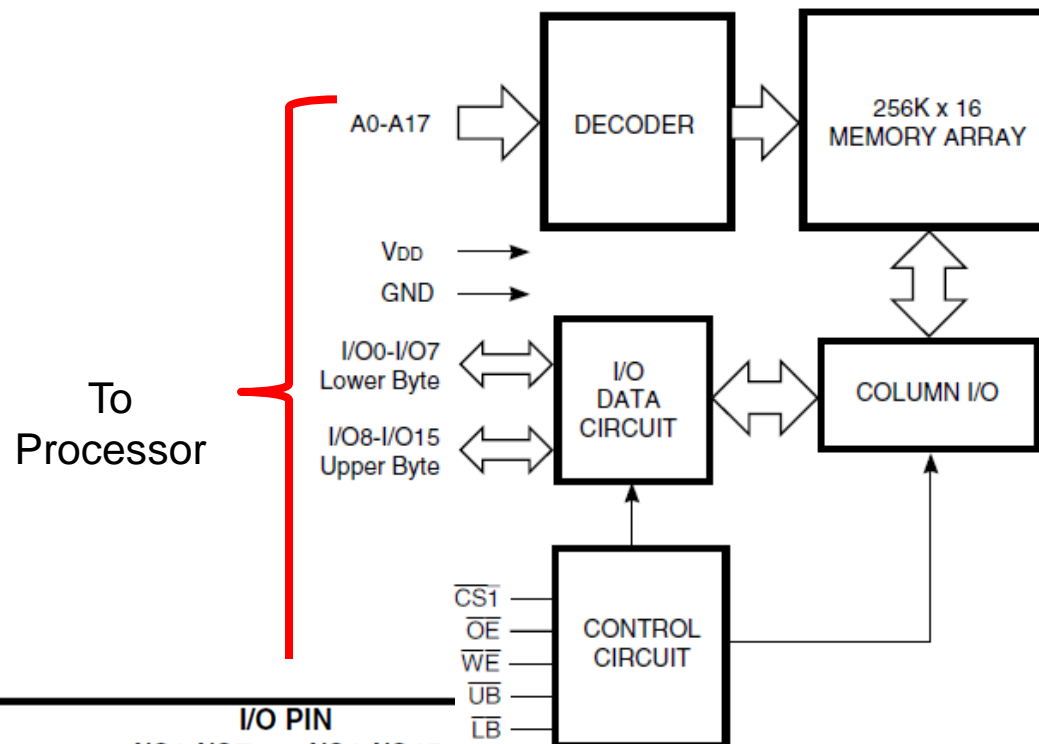
SST39VF3201B



3.7.4. The EMC: Example



IS62WV25616



TRUTH TABLE

Mode	\overline{WE}	$\overline{CS1}$	\overline{OE}	\overline{LB}	\overline{UB}	I/O PIN	
						I/O0-I/O7	I/O8-I/O15
Not Selected	X	H	X	X	X	High-Z	High-Z
	X	X	X	H	H	High-Z	High-Z
Output Disabled	H	L	H	L	X	High-Z	High-Z
	H	L	H	X	L	High-Z	High-Z
Read	H	L	L	L	H	DOUT	High-Z
	H	L	L	H	L	High-Z	DOUT
	H	L	L	L	L	DOUT	DOUT
Write	L	L	X	L	H	DIN	High-Z
	L	L	X	H	L	High-Z	DIN
	L	L	X	L	L	DIN	DIN

3.7.4. The EMC: Example

1. Fill in the following table related to the used external memory map:

Memory (chip)	Type	Capacity	Initial Add.	Data length
SST39VF3201B				
IS62WV25616BLL				

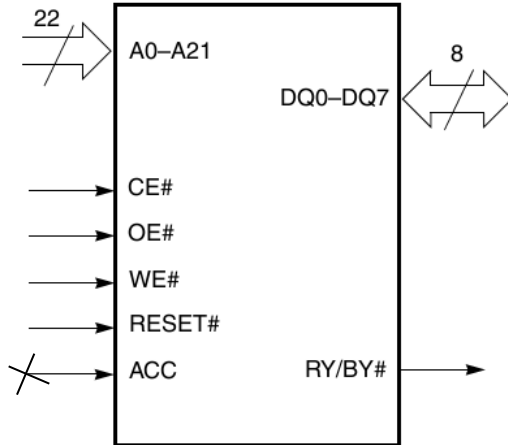
2. Fill in the following table related to the type of decoding used in the schematic:

Memory (chip)	Decoding Type	Logic address of the first position in the chip
SST39VF3201B		
IS62WV25616BLL		

3.7.4. The EMC: Example



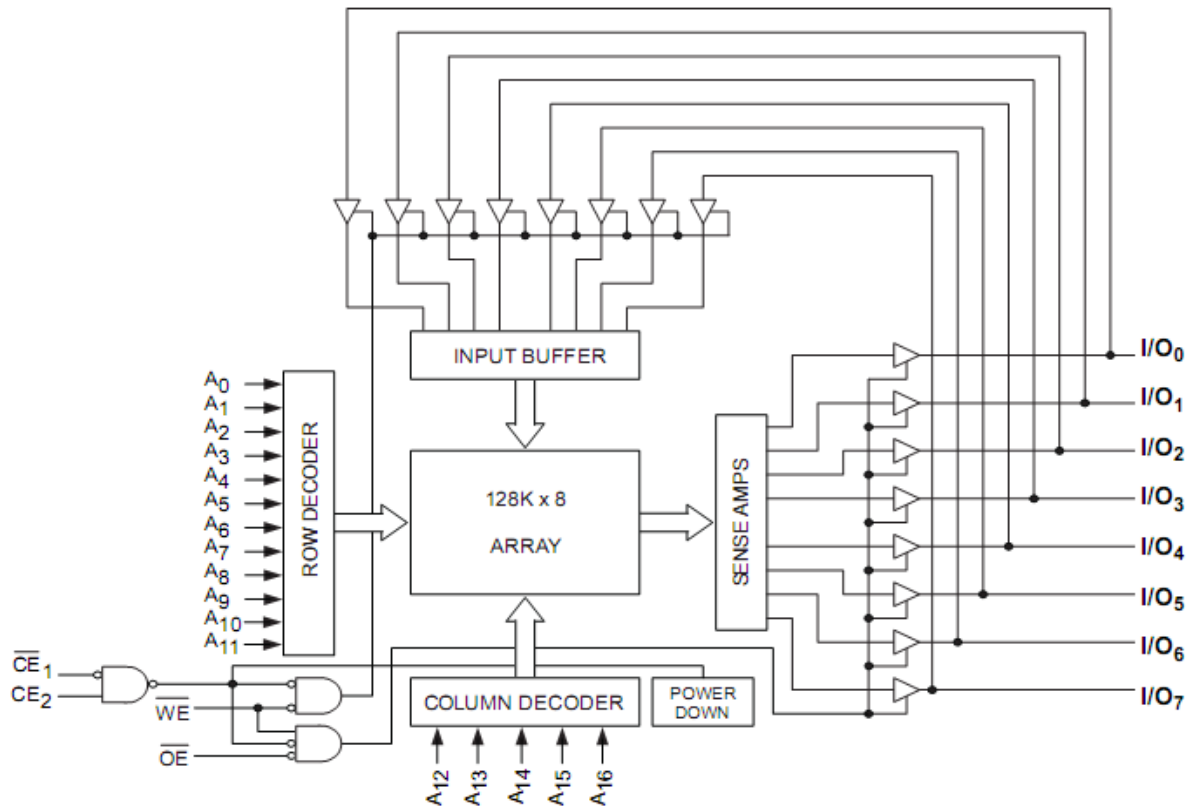
3. Modify the schematic in order to implement the space occupied by the SST39VF3201B-70 by chips of the S29AL032D70TAI00, preserving the data length used in that space



3.7.4. The EMC: Example



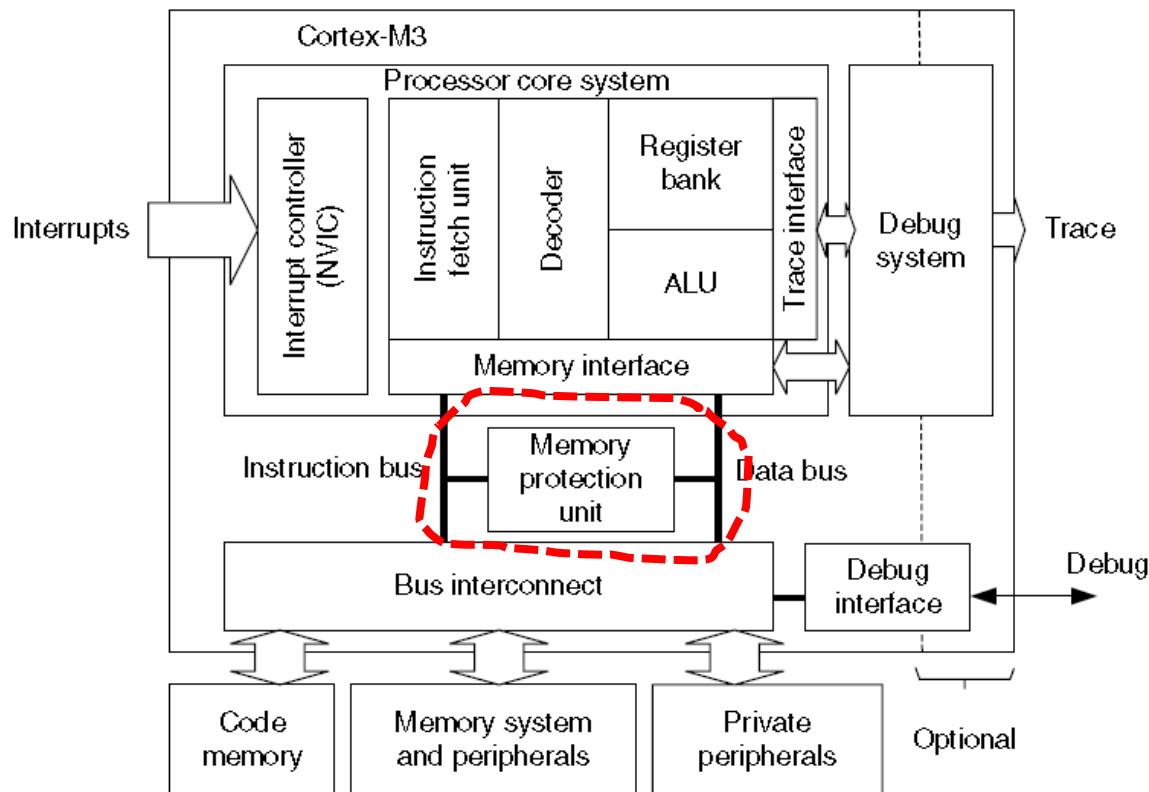
4. Do the same as in 3, implementing the space occupied by the IS62WV25616BLL-55TLI by chips of the CY62128E, preserving the data length used in that space



3.8. The MPU. General description

◆ How does MPU work?

- ◆ Monitors I-bus, D-bus and System-bus



3.8. The MPU. General description

- ❑ The **Memory Protection Unit (MPU)** is a common element in complex embedded systems that...
 - Provides memory protection features, making based systems more robust
 - Included in Cortex-M3 (and LPC17XX specifically) and many other μC
 - Sets up the protection by defining the memory map as a number of regions, with a specific functionality, and type of use and accesses allowed
 - ❑ Up to 8 regions can be defined
 - ❑ MPU regions can be overlapped. If a memory location falls on two regions, the memory access attributes and permission will be the highest-numbered region
 - ❑ It is also possible to define a default background memory map for privileged accesses (PRIVDEFENA)
- ◆ Accesses to memory locations that are not defined in the MPU or not permitted will cause the Memory Management Fault

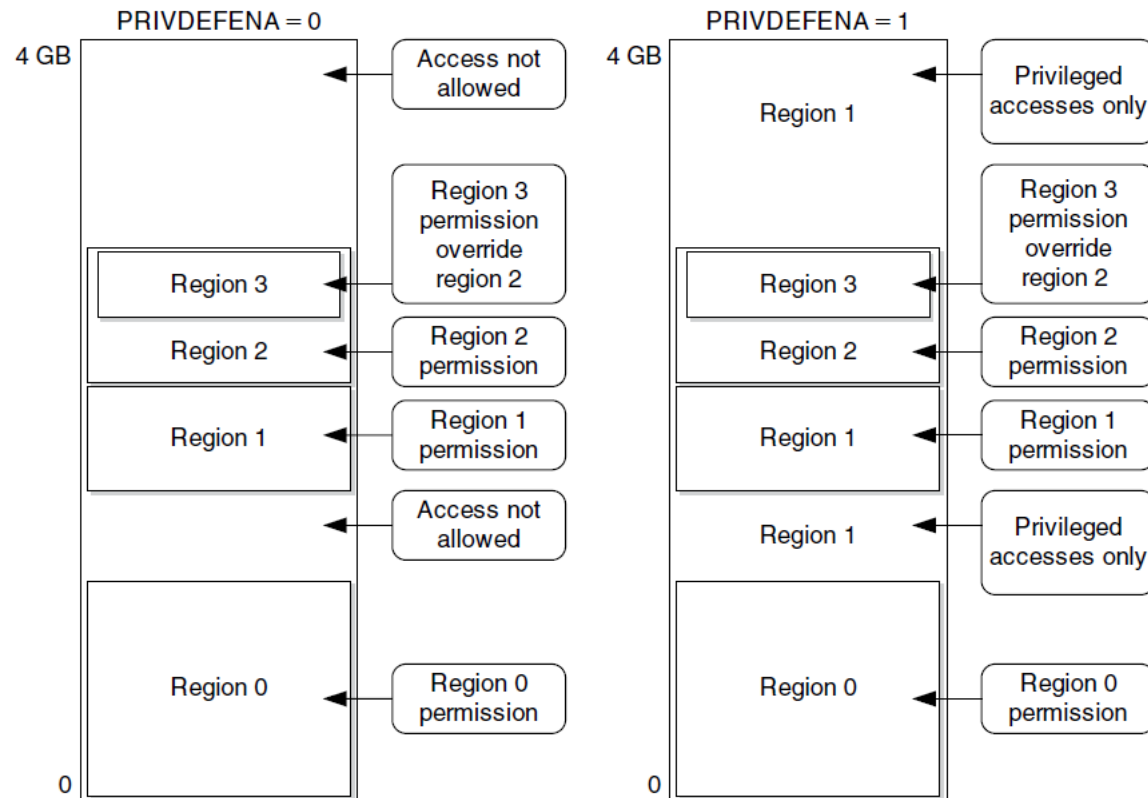
3.8. *The MPU. General description*

- What is MPU used for?
 - Preventing user applications from corrupting data used by the operating system
 - Separating data between tasks by blocking from accessing others' data
 - Allowing memory regions to be defined as read-only so that data can be protected
 - Detecting unexpected memory accesses (for example, stack corruption)
-

3.8. The MPU. General description

◆ An example of use:

- ◆ PRIVDEFENA differs between normal map and default background map for privileged accesses



3.8.1. The MPU. Registers



- MPU has to be configured in order to be enabled

Table 13.1 MPU Type Register (0xE000ED90)

Bits	Name	Type	Reset Value	Description
23:16	IREGION	R	0	Number of instruction regions supported by this MPU; because ARMv7-M architecture uses a unified MPU, this is always 0
15:8	DREGION	R	0 or 8	Number of regions supported by this MPU; in the Cortex-M3, this is either 0 (MPU not present) or 8 (MPU present)
0	SEPARATE	R	0	This is always 0, as the MPU is unified

Table 13.2 MPU Control Register (0xE000ED94)

Bits	Name	Type	Reset Value	Description
2	PRIVDEFENA	R/W	0	Privileged default memory map enable; when set to 1 and if the MPU is enabled, the default memory map will be used for privileged accesses as a background region. If this bit is not set, the background region is disabled and any access not covered by any enabled region will cause a fault.
1	HFNMENA	R/W	0	If set to 1, it enables the MPU during the hard fault handler and nonmaskable interrupt (NMI) handler; otherwise, the MPU is not enabled (bypassed) for the hard fault handler and NMI.
0	ENABLE	R/W	0	It enables the MPU if set to 1.

3.8.1. The MPU. Registers



Table 13.4 MPU Region Base Address Register (0xE000ED9C)

Bits	Name	Type	Reset Value	Description
31:N	ADDR	R/W	—	Base address of the region; N is dependent on the region size—for example, a 64 KB size region will have a base address field of [31:16].
4	VALID	R/W	—	If this is 1, the REGION defined in bit [3:0] will be used in this programming step; otherwise, the region selected by the MPU Region Number register is used.
3:0	REGION	R/W	—	This field overrides the MPU Region Number register if VALID is 1; otherwise, it is ignored. Because eight regions are supported in the Cortex-M3 MPU, the region number override is ignored if the value of the REGION field is larger than 7.

Table 13.5 MPU Region Base Attribute and Size Register (0xE000EDA0)

Bits	Name	Type	Reset Value	Description
31:29	Reserved	—	—	—
28	XN	R/W	—	Instruction Access Disable (1 = disable instruction fetch from this region; an attempt to do so will result in a memory management fault)
27	Reserved	—	—	—
26:24	AP	R/W	—	Data Access Permission field
23:22	Reserved	—	—	—
21:19	TEX	R/W	—	Type Extension field
18	S	R/W	—	Shareable
17	C	R/W	—	Cacheable
16	B	R/W	—	Bufferable
15:8	SRD	R/W	—	Subregion disable
7:6	Reserved	—	—	—
5:1	REGION SIZE	R/W	—	MPU Protection Region size
0	ENABLE	R/W	—	Region enable